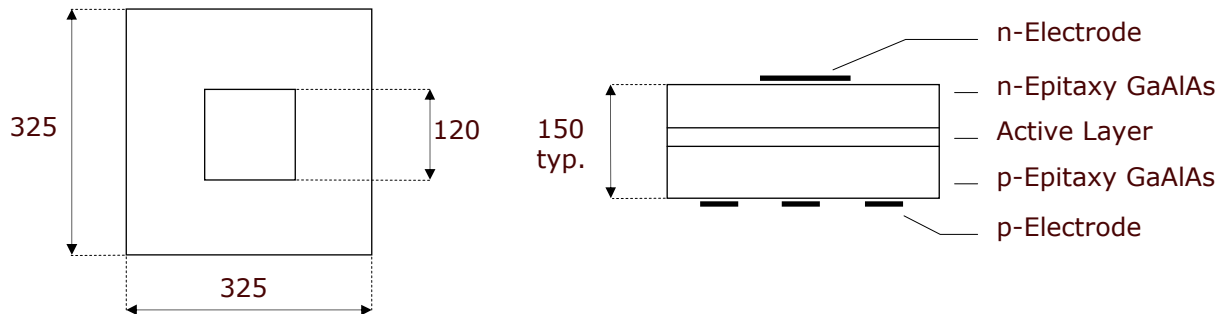


INFRA-RED

Item No.: 127141 L

1. This specification applies to GaAlAs / GaAlAs LED Chips (substrate removed)
2. Structure
 - 2.1 Mesa structure
 - 2.2 Electrodes

| | |
|------------------|----------|
| p-side (anode) | Au alloy |
| n-side (cathode) | Au alloy |
3. Outlines (dimensions in microns)



Wire bond contacts can also have a spider shape

4. Electrical and optical characteristics (T=25°C)

| Parameter | Symbol | Conditions | min | typ | max | Unit |
|-----------------|-------------|--------------------------------|-----|------|------|------|
| Forward voltage | V_F | $I_F = 20 \text{ mA}$ | | 1,70 | 2,10 | V |
| Reverse voltage | V_R | $I_R = 10 \text{ }\mu\text{A}$ | 5 | | | V |
| output Power * | Φ_e | $I_F = 20 \text{ mA}$ | 2,0 | 2,4 | | mW |
| Switching time | t_r, t_f | $I_F = 20 \text{ mA}$ | | 40 | | ns |
| Peak wavelength | λ_p | $I_F = 20 \text{ mA}$ | | 720 | | nm |

Power measurement at OSA on gold plate

5. Packing

Dice on adhesive film with 1) wire bond side on top
2) back contact on top

6. Labeling

| Type | Lot No. | Φ_e typ min max | Quantity |
|------|---------|----------------------------|----------|
| | | | |